## 505979650 03/23/2020 PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:		NEW ASSIGNMI	ENT			
NATURE OF CONVEYANCE:		ASSIGNMENT	ASSIGNMENT			
CONVEYING PARTY DA	ATA					
		Name			Execution Date	
CHIAO-CHUN HSU					03/03/2020	
CHIH-MING CHEN				03/03/2020		
CHUNG-YI YU				03/03/2020		
LUNG YUAN PAN				03/03/2020		
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State/Country:	TAIWAN					
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PROPERTY NUMBERS Total: 1 Property Type		Numbe	r	]		
Application Number: 1680		16801350				
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NAME OF SUBMITTER:		DAVID W. POTA	SHNIK			
SIGNATURE:		/David W. Potasł	nnik/			
DATE SIGNED:		03/23/2020				
Fotal Attachments: 6						

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#### PATENT ASSIGNMENT

#### PARTIES TO THE ASSIGNMENT

Assignor(s): Chiao-Chun Hsu

Assignor(s): Chih-Ming Chen

<u>Assignor(s):</u> Chung-Yi Yu

<u>Assignor(s):</u> Lung Yuan Pan

<u>Assignee:</u> Taiwan Semiconductor Manufacturing Co., Ltd. No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park Hsin-Chu, Taiwan 300-77 Republic of China

### AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled

## "SELF-ALIGNED DIELECTRIC LINER STRUCTURE FOR PROTECTION IN MEMS COMB

#### ACTUATOR" for which:

a non-provisional application for United States Letters Patent:

was executed on even date preparatory to filling (each inventor should sign this Assignment on the same day as he/she signs the Declaration); or

was filed on \_\_\_\_\_ and accorded U.S. Serial No. \_\_\_\_\_; or

I hereby authorize and request my attorney associated with Customer No.

107476, to insert on the designated lines below the filing date and application

number of said application when known:

U.S. Serial No.

filed on

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## PATENT REEL: 052194 FRAME: 0070

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

## PATENT REEL: 052194 FRAME: 0071

## TSMC Docket No. P20191761US00 Docket No. TSMCP1097US

>0>0/3/3/3 Date

Chas-Chun Hsu

Name 1<sup>st</sup> Inventor Chiao-Chun Hsu

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PATENT REEL: 052194 FRAME: 0072 

## TSMC Docket No. P20191761US00 Docket No. TSMCP1097US

Date

سال السني المنك Name 2<sup>nd</sup> Inventor Chih-Ming Chen

PATENT REEL: 052194 FRAME: 0073

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# TSMC Docket No. P20191761US00 Docket No. TSMCP1097US

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2022/3./3

Date

Glung Yr Yn Name - 3<sup>rd</sup> Inventor Chung-Yi Yu

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## TSMC Docket No. P20191761US00 Docket No. TSMCP1097US

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2870.3.37

Date

Lung Yuan Pan Name 4" Inventor Lung Yuan Pan

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## PATENT REEL: 052194 FRAME: 0075

**RECORDED: 03/23/2020**